

#### **Features**

- High Dense Cell Design for Extremely Low R<sub>DS(ON)</sub>
- · Rugged and Reliable
- · Surface Mount Package
- Epoxy Meets UL 94 V-0 Flammability Rating
- · Moisture Sensitivity Level 1
- Halogen Free. "Green" Device (Note 1)
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

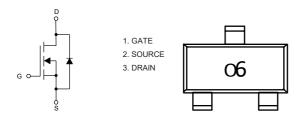
# **Maximum Ratings**

- Operating Junction Temperature Range: -55°C to +150°C
- Storage Temperature: -55°C to +150°C
- Thermal Resistance: 100°C/W Junction to Ambient

Parameter	Symbol	Rating	Unit
Drain -source Voltage	V <sub>DS</sub>	30	V
Gate -Source Voltage	V <sub>GS</sub>	±20	V
Drain Current-Continuous(Note 2,3)	I <sub>D</sub>	3.16	Α
Drain Current-Pulse	I <sub>DM</sub>	20	Α
Source Current-Continuoud <sup>(Note 2,3)</sup>	Is	0.62	W
Power Dissipation	P <sub>D</sub>	0.75	W

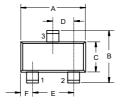
Note: 1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

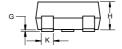
## **Internal Structure and Marking Code**



# **N-Channel MOSFET**



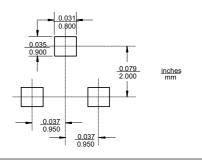






DIMENSIONS						
DIM	INCHES		MM		NOTE	
	MIN	MAX	MIN	MAX	NOIL	
Α	0.110	0.120	2.80	3.04		
В	0.083	0.104	2.10	2.64		
С	0.047	0.055	1.20	1.40		
D	0.034	0.041	0.85	1.05		
Е	0.067	0.083	1.70	2.10		
F	0.018	0.024	0.45	0.60		
G	0.0004	0.006	0.01	0.15		
Н	0.035	0.043	0.90	1.10		
J	0.003	0.007	0.08	0.18		
K	0.012	0.020	0.30	0.51		
L	0.007	0.020	0.20	0.50		

## Suggested Solder Pad Layout





# **ELECTRICAL CHARACTERISTICS (Ta=25°C unless otherwise specified)**

Parameter	Symbol	Test conditions	Min	Тур	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	30			V
Gate-Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS}=V_{GS}$ , $I_D=250\mu A$	1.0		3.0	V
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =± 20V, V <sub>DS</sub> =0V			±100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V			0.5	μΑ
Drain-Source On-Resistance <sup>(Note 4)</sup>		V <sub>GS</sub> =10V, I <sub>D</sub> =3.5A		38 47		mΩ
	R <sub>DS(on)</sub>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =2.8A		52	65	11177
Forward Transconductance <sup>(Note 4)</sup>	g <sub>FS</sub>	V <sub>DS</sub> =4.5V, I <sub>D</sub> =2.5A		7.0		S
Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =1.25A		0.8	1.2	V
Dynamic Characteristics						
Input Capacitance	C <sub>iss</sub>			305		
Output Capacitance	C <sub>oss</sub>	$V_{DS}$ =15V, $V_{GS}$ =0V, f=1MHz		65		pF
Reverse Transfer Capacitance	C <sub>rss</sub>			29		
Gate Resistance	$R_g$	f=1MHz	2.5	5	7.5	Ω
Gate Charge	$Q_g$	V <sub>DS</sub> =15V,V <sub>GS</sub> =5V,I <sub>D</sub> =2.5A		3.0	4.5	
Total Gate Charge	Q <sub>gt</sub>			6	9	nC
Gate-Source Charge	$Q_{gs}$	$V_{DS}$ =15V, $V_{GS}$ =10V, $I_{D}$ =2.5A		1.6		110
Gate-Drain Charge	$Q_{gd}$			0.6		
Switching Characteristics						
Turn-On Delay Time	t <sub>d(on)</sub>			7	11	
Turn-On Rise Time	t <sub>r</sub>	$V_{DD}$ =15V,R <sub>L</sub> =15 $\Omega$ ,V <sub>GEN</sub> =10V, I <sub>D</sub> =1A,R <sub>G</sub> =6 $\Omega$		12	18	
Turn-Off Delay Time	t <sub>d(off)</sub>	10 173,143-032		14	25	ns
Turn-Off Fall Time	t <sub>f</sub>			6	10	

#### Note:

- 2. Surface Mounted on 1" x1" FR4 Board, t<5s.
- 3. Pulse Width Limited by Maximum Junction Temperature.
- 4. Pulse Test: Pulse Width≤300µs, Duty Cycle ≤ 2%.



### **Curve Characteristics**

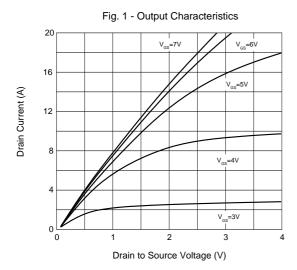
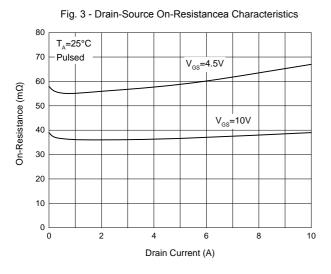
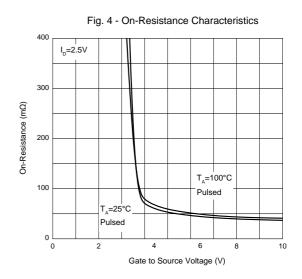
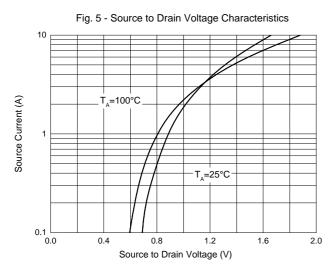
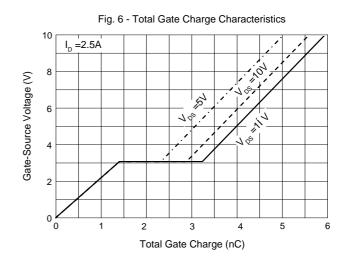


Fig. 2 - Transfer Characteristics











## **Ordering Information**

Device	Packing
Part Number-TP	Tape&Reel:3Kpcs/Reel

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